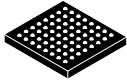


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

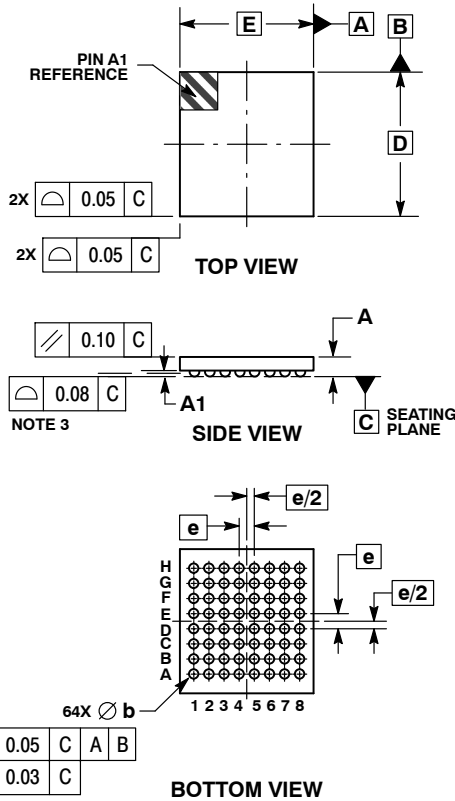
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SCALE 2:1

WLCSP64, 4.77x4.42
CASE 567HW
ISSUE O

DATE 23 JUL 2013

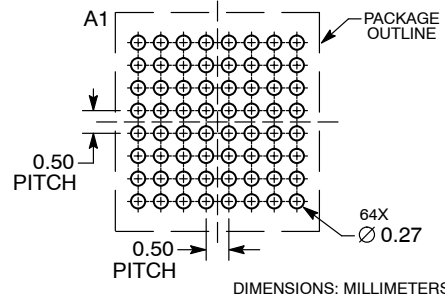


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.66
A1	0.13	0.23
b	0.22	0.34
D	4.77 BSC	
E	4.42 BSC	
e	0.50 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP64, 4.77X4.42	PAGE 1 OF 1

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